Features

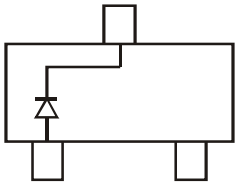
- Ultra-Small Surface Mount Package
- Very Low Leakage Current
- **Lead Free/RoHS Compliant (Note 2)**
- **Qualified to AEC-Q101 Standards for High Reliability**
- **"Green" Device (Note 3 and 4)**

Mechanical Data

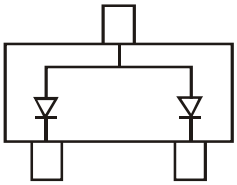
- Case: SOT-523
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020C
- Terminals: Solderable per MIL-STD-202, Method 208
- Lead Free Plating (Matte Tin Finish annealed over Alloy 42 leadframe).
- Polarity: See Diagrams Below
- Marking Information: See Diagrams Below and Page 3
- Ordering Information: See Page 2
- Weight: 0.002 grams (approximate)

SOT-523

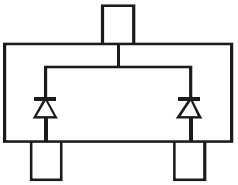
Top View



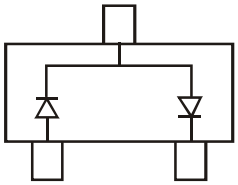
BAS116T Marking: 50



BAW156T Marking: 53



BAV170T Marking: 51



BAV199T Marking: 52

Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic		Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage		V_{RRM} V_{RWM} V_R	85	V
RMS Reverse Voltage		$V_{R(RMS)}$	60	V
Forward Continuous Current (Note 1)	Single Diode Double Diode	I_{FM}	215 125	mA
Repetitive Peak Forward Current		I_{FRM}	500	mA
Non-Repetitive Peak Forward Surge Current	@ t = 1.0μs @ t = 1.0ms @ t = 1.0s	I_{FSM}	4.0 1.0 0.5	A

Thermal Characteristics

Characteristic		Symbol	Value	Unit
Power Dissipation	(Note 1)	P_d	150	mW
Thermal Resistance Junction to Ambient Air	(Note 1)	$R_{\theta JA}$	833	°C/W
Operating and Storage Temperature Range		T_j , T_{STG}	-65 to +150	°C

Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic		Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage	(Note 5)	$V_{(BR)R}$	85	—	—	V	I_R = 100μA
Forward Voltage		V_F	—	—	0.90 1.0 1.1 1.25	V	I_F = 1.0mA I_F = 10mA I_F = 50mA I_F = 150mA
Leakage Current	(Note 5)	I_R	—	—	5.0 80	nA nA	V_R = 75V V_R = 75V, T_j = 150°C
Total Capacitance		C_T	—	2	—	pF	V_R = 0, f = 1.0MHz
Reverse Recovery Time		t_{rr}	—	—	3.0	μs	I_F = I_R = 10mA, I_{rr} = 0.1 x I_R, R_L = 100Ω

Notes:
1. Device mounted on FR-4 PC board with recommended pad layout, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.
2. No purposefully added lead.
3. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead_free/index.php.
4. Product manufactured with Date Code UO (week 40, 2007) and newer are built with Green Molding Compound. Product manufactured prior to Date Code UO are built with Non-Green Molding Compound and may contain Halogens or Sb2O3 Fire Retardants.
5. Short duration pulse test used to minimize self-heating effect.

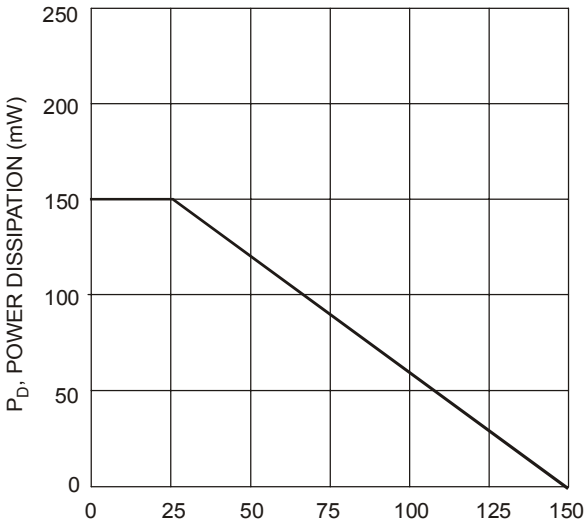


Fig. 1 Power Derating Curve

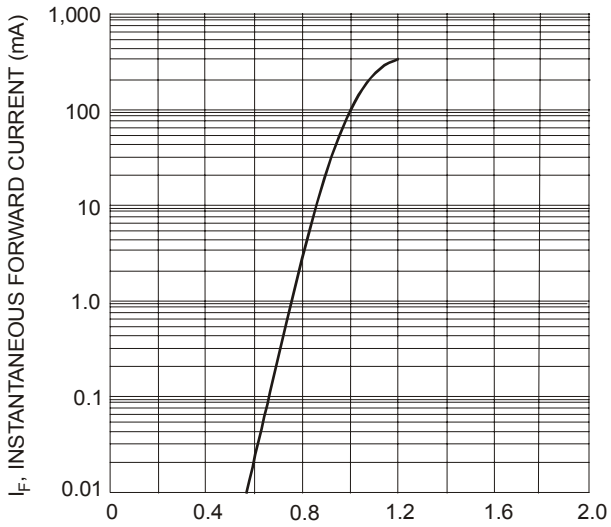


Fig. 2 Typical Forward Characteristics

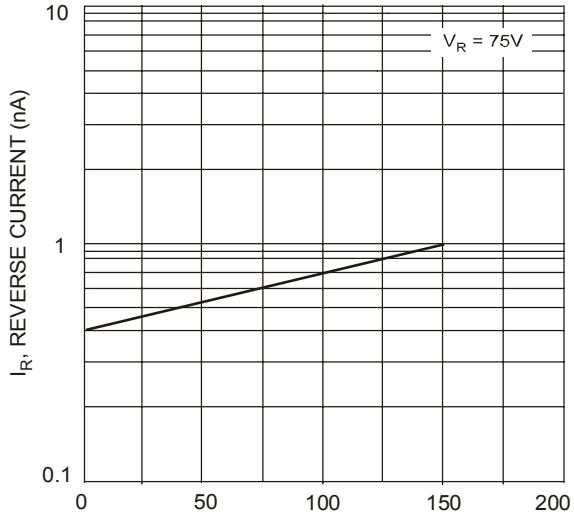


Fig. 3 Typical Reverse Characteristics

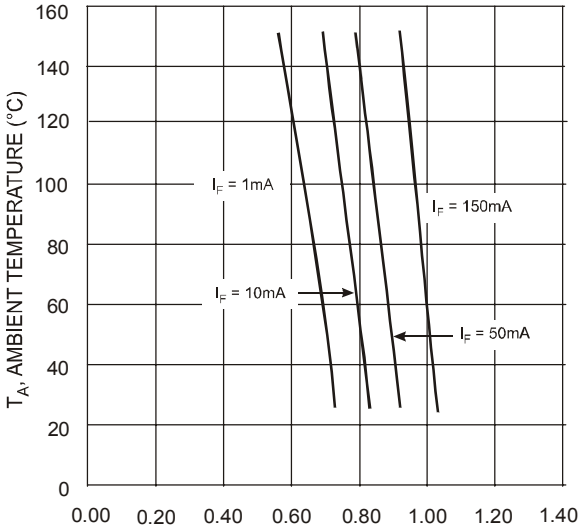


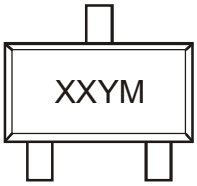
Fig. 4 Typical Forward Voltage vs Ambient Temperature

Ordering Information (Note 6)

Part Number	Case	Packaging
BAS116T-7-F	SOT-523	3000/Tape & Reel
BAW156T-7-F	SOT-523	3000/Tape & Reel
BAV170T-7-F	SOT-523	3000/Tape & Reel
BAV199T-7-F	SOT-523	3000/Tape & Reel

Notes: 6. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

Marking Information



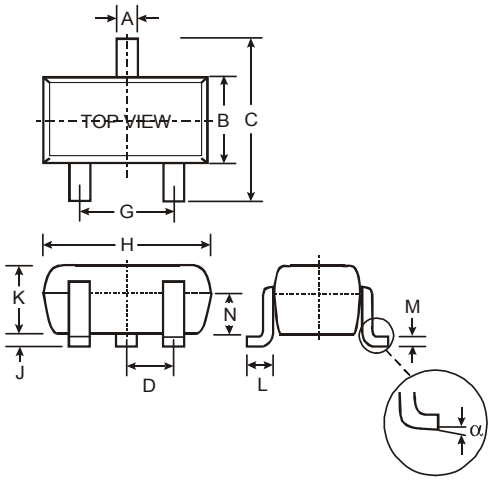
XX = Product Type Marking Code (See Page 1, e.g. 50 = BAS116T)
YM = Date Code Marking
Y = Year (ex: N = 2002)
M = Month (ex: 9 = September)

Date Code Key

Year	2001	2002	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012
Code	M	N	P	R	S	T	U	V	W	X	Y	Z

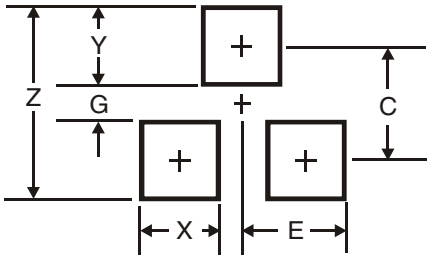
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Package Outline Dimensions



SOT-523			
Dim	Min	Max	Typ
A	0.15	0.30	0.22
B	0.75	0.85	0.80
C	1.45	1.75	1.60
D	—	—	0.50
G	0.90	1.10	1.00
H	1.50	1.70	1.60
J	0.00	0.10	0.05
K	0.60	0.80	0.75
L	0.10	0.30	0.22
M	0.10	0.20	0.12
N	0.45	0.65	0.50
α	0°	8°	—
All Dimensions in mm			

Suggested Pad Layout



Dimensions	Value (in mm)
Z	1.9
G	0.9
X	0.5
Y	0.5
C	1.4
E	0.5